

L Number	Hits	Search Text	DB	Time stamp
1	4	5694481.pn.,6285369.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 17:12
-	23	viewdraw	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 12:55
-	0	schematic near3 edit\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 13:01
-	470	schematic near3 edit\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 13:23
-	23	(schematic near3 edit\$3) and (cut same paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 13:30
-	246	(schematic near3 edit\$3) and ((semi adj conduct\$5) or IC or Chip or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 13:33
-	2	(schematic near3 edit\$3) near5 ((semi adj conduct\$5) or IC or Chip or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:51
-	4471	382/141,144,145,147,151,284,294;29/833;438/16.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:50
-	1349	382/141,144,145,147,151,284,294;29/833;438/16. and schematic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:51
-	3	382/141,144,145,147,151,284,294;29/833;438/16. and (schematic near3 edit\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:51

-	793	(382/141,144,145,147,151,284,294;29/833;438/1612) and schematic) and ((semi adj conduct\$5) or IC or Chip or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:55
-	145	(382/141,144,145,147,151,284,294;29/833;438/1612) and schematic) and (((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (draw\$6 or plan\$1 or diagram\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:07
-	48	((382/141,144,145,147,151,284,294;29/833;438/1612) and schematic) and (((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (draw\$6 or plan\$1 or diagram\$1))) and (edit\$5 or modify\$5 or alter\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:56
-	29662	(((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (design))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 10:48
-	10	(((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (design)) same (schematic near3 edit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 12:14
-	20	CAE same (((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (design))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 10:38
-	476	((CAE or CAD) and (photomosaic\$1 or mosaic\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 10:48
-	29697	(((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (design))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 10:48
-	43	(((CAE or CAD) and (photomosaic\$1 or mosaic\$1))) and (((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (design)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 10:48
-	2	(((semi adj conduct\$5) or IC or Chip or semiconductor) near4 (design)) same (schematic near3 edit\$3) and (design near3 analysis)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 12:16

-	4	5086477.pn.,5191213.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 12:54
-	128	((reverse near3 engineer\$3) near5 (IC or (integrated near3 circuit\$)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 14:43
-	57	((reverse near3 engineer\$3) near5 (IC or (integrated near3 circuit\$))) and schematic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 14:44
-	11	((reverse near3 engineer\$3) near5 (IC or (integrated near3 circuit\$))) and schematic) and edit\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 14:50
-	2	4766516.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 14:51
-	26	(US-6289116-\$ or US-6236746-\$ or US-5086477-\$ or US-5191213-\$ or US-5185812-\$ or US-6292766-\$ or US-5675499-\$ or US-6553543-\$ or US-5170263-\$ or US-5694481-\$ or US-5629860-\$ or US-5634113-\$ or US-6272668-\$ or US-6077308-\$ or US-6549222-\$ or US-5530372-\$ or US-6738957-\$ or US-5946478-\$ or US-5850348-\$ or US-5553001-\$ or US-4766516-\$ or US-6598210-\$ or US-6591155-\$ or US-6546539-\$).did. or (US-5740071-\$ or US-5901064-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/06 10:47
-	2	((US-6289116-\$ or US-6236746-\$ or US-5086477-\$ or US-5191213-\$ or US-5185812-\$ or US-6292766-\$ or US-5675499-\$ or US-6553543-\$ or US-5170263-\$ or US-5694481-\$ or US-5629860-\$ or US-5634113-\$ or US-6272668-\$ or US-6077308-\$ or US-6549222-\$ or US-5530372-\$ or US-6738957-\$ or US-5946478-\$ or US-5850348-\$ or US-5553001-\$ or US-4766516-\$ or US-6598210-\$ or US-6591155-\$ or US-6546539-\$).did. or (US-5740071-\$ or US-5901064-\$).did.) and (cutt\$3 and past\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 10:48

-	159	(cutt\$3 and past\$5) same schematic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 10:50
-	108	(cutt\$3 same past\$5) same schematic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 10:59
-	52	(extract\$6 same past\$5) same schematic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 10:59
-	1393	(CAD or CAE) same ((cut same paste) or edit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:44
-	11	(CAD or CAE) same (cut same paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:50
-	20	(microsoft adj word) same (cut same paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:53
-	11457	OLE	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 11:01
-	3034	Object near3 linking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 11:02
-	1113	Object near3 linking near3 embed\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 11:02
-	256	(Object near3 linking near3 embed\$4) and schematic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 11:05

-	86	(Object near3 linking near3 embed\$4) and schematic and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 11:07
-	47	(Object near3 linking near3 embed\$4) and schematic and (circuit near3 design)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 11:07
-	1	(schematic near3 (layout\$ or design\$3)) and (edit\$4 near3 (cut\$3 and past\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 14:13
-	12	(schematic near3 (layout\$ or design\$3)) and (edit\$4 same (cut\$3 and past\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 14:17
-	25	(schematic near3 (layout\$ or design\$3 or edit\$)) and (edit\$4 same (cut\$3 and past\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 14:19
-	13	((schematic near3 (layout\$ or design\$3 or edit\$)) and (edit\$4 same (cut\$3 and past\$4))) not ((schematic near3 (layout\$ or design\$3)) and (edit\$4 same (cut\$3 and past\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 14:19
-	9	"CAE" and (edit\$4 same (cut\$3 and past\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 14:32
-	0	6285369.pn. and (serach or find)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 15:38
-	0	6285369.pn. and (search or find)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 15:37
-	2	6285369.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 15:38

-	1	6285369.pn. and database	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/07 15:38
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